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APPLICANTS

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** CONTINUING DATA ***** *STM (none)*

** FOREIGN APPLICATIONS ***** *STM*
 JAPAN 2003-103862 04/08/2003

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Foreign Priority claimed 35 USC 119 (a-d) conditions met Verified and Acknowledged	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance <i>Abdulhameed</i> Examiner's Signature	<i>STM</i> Initials	STATE OR COUNTRY JAPAN	SHEETS DRAWING 6	TOTAL CLAIMS 8	INDEPENDENT CLAIMS 3
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ADDRESS

23400
 POSZ & BETHARDS, PLC
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TITLE

Method of resin-sealing a semiconductor device, resin-sealed semiconductor device, and forming die for
 resin-sealing the semiconductor device

FILING FEE RECEIVED 770	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
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